

Our Solutions, Your Value

Model ID	NPM-D2						
Front head	Rear head	16-nozzle head	12-nozzle head	8-nozzle head	2-nozzle head	Dispensing head	No head
16-nozzle head		NM-EJM5D				NM-EJM5D-MD	NM-EJM5D
12-nozzle head							
8-nozzle head							
2-nozzle head							
Dispensing head							NM-EJM5D-D
Inspection head							NM-EJM5D-A
No head						NM-EJM5D-D	
PCB dimensions*1	Dual-lane mode	L 50 mm × W 50 mm ~ L 510 mm × W 300 mm			PCB exchange time	Dual-lane mode	0 s* *No 0s when cycle time is 4.5 s or less
	Single-lane mode	L 50 mm × W 50 mm ~ L 510 mm × W 590 mm				Single-lane mode	3.9 s
Electric source	3-phase AC 200, 220, 380, 400, 420, 480 V 2.5 kVA						
Pneumatic source*2	0.5 MPa, 100 L /min (A.N.R.)						
Dimensions*2	W 835 mm × D 2 652 mm*3 × H 1 444 mm*4						
Mass	1 620 kg (Only for main body; This differs depending on the option configuration.)						

Placement head	16-nozzle head (With Dual Heads)	12-nozzle head (With Dual Heads)	8-nozzle head (With Dual Heads)	2-nozzle head (With Dual Heads)
Placement speed/Max. speed	70 000cph (0.051 s/chip)	62 500cph (0.058 s/chip)	40 000cph (0.090 s/chip)	8 500cph (0.423 s/QFP)
IPC9850(1608)	53 800cph*5	48 000cph*5	—	—
Placement accuracy(Cpk≥1)	±40 μm / chip	±40 μm / chip	±40 μm / chip ±30 μm/QFP □12 mm ~ □32 mm ±50 μm/QFP □12 mm Under	±30 μm / QFP
Component dimensions (mm)	(01005*)0402 chip*6 to L 6 × W 6 × T 3 (01005*)0402 chip*6 to L 12 × W 12 × T 6.5		(01005*)0402 chip*6 to L 32 × W 32 × T 12	(0201*)0603 chip to L 100 × W 90 × T 28
Component supply	Tape: 8 / 12 / 16 / 24 / 32 / 44 / 56 mm 8 mm tape : Max. 68 (double feeder, small real)		Tape: 8 to 56 / 72 / 88 / 104 mm	
	Stick, Tray		Stick: Max. 8, Tray : Max. 20 (per tray feeder)	

Dispensing head	Dot dispensing	Draw dispensing
Dispensing speed	0.16 s/dot (Condition : XY=10 mm, Z=less than 4 mm movement, No θ rotation)	3.75 s/component (Condition: 30 mm x 30 mm corner dispensing)
Adhesive position accuracy(Cpk≥1)	± 75 μm/dot	± 100 μm/component
Applicable components	1608 chip to SOP, PLCC, QFP, Connector, BGA, CSP	SOP, PLCC, QFP, Connector, BGA, CSP

Inspection head	2D inspection head (A)	2D inspection head (B)
Resolution	18 μm	9 μm
View size	44.4 mm × 37.2 mm	21.1 mm × 17.6 mm
Inspection processing time	Solder Inspection*8: 0.35s/View size Component Inspection*8: 0.5s/View size	
Inspection object	Solder Inspection*8: Chip component : 100 μm × 150 μm or more (0603 / 0201* or more) Package component : φ150 μm or more Component Inspection*8: Square chip (0603 / 0201* or more), SOP, QFP (a pitch of 0.4mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector, Network resistor, Transistor, Diode, Inductor, Tantalum capacitor, Melf	Chip component : 80 μm × 120 μm or more (0402 / 01005* or more) Package component : φ120 μm or more Component Inspection*8: Square chip (0402 / 01005* or more), SOP, QFP (a pitch of 0.3mm or more), CSP, BGA, Aluminum electrolysis capacitor, Volume, Trimmer, Coil, Connector, Network resistor, Transistor, Diode, Inductor, Tantalum capacitor, Melf
Inspection items	Solder Inspection*8: Oozing, blur, misalignment, abnormal shape, bridging Component Inspection*8: Missing, shift, flipping, polarity, foreign object inspection*7	
Inspection position accuracy (Cpk≥1)*9	± 20 μm	± 10 μm
No. of inspection	Solder Inspection*8: Max. 30 000 pcs./machine (No. of components : Max. 10 000 pcs./machine) Component Inspection*8: Max. 10 000 pcs./machine	

* Placement tact time, inspection time and accuracy values may differ slightly depending on conditions

* Please refer to the specification booklet for details.

*1 : As board transfer standard differ, it cannot be linked with dual-lane spec. NPM (NM-EJM9B).

*2 : Only for main body

*3 : Dimension D including tray feeder : 2 683 mm
Dimension D including feeder cart : 2 728 mm

*4 : Excluding monitor and signal tower

*5 : It is the reference value of the tact time by the IPC9850 conformity.

*6 : The 0402 chip requires a specific nozzle/feeder.

*7 : Foreign object is available to chip components.

*8 : One head cannot handle solder inspection and component inspection at the same time.

*9 : This is the solder inspection position accuracy measured by our reference using our glass PCB per plane calibration. It may be affected by sudden change of ambient temperature.

⚠ Safety Cautions

● Please read the User's Manual carefully to familiarize yourself with safe and effective usage procedures.

● To ensure safety when using this equipment all work should be performed according to that as stated in the supplied Operating Instructions. Read your operating instruction manual thoroughly.

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ISO 14001 Panasonic Group builds Environmental Management System in the factories of the world and acquires the International Environmental Standard ISO 14001:2004.

Inquiries...

Panasonic Factory Solutions Co., Ltd.
Corporate Sales Division

1375 Kamisukiawara, Showa-cho, Nakakoma-gun, Yamanashi 409-3895, Japan
TEL +81-55-275-9148
FAX +81-55-275-6269

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Panasonic

2013
Electronics Assembly System

catalog

PRODUCTION MODULAR



NPM

NEXT PRODUCTION MODULAR

Manufacturing Process Innovation



Model Name

NPM-D2

Model No. NM-EJM5D

Model No. NM-EJM5D-MD

Model No. NM-EJM5D-D

Model No. NM-EJM5D-MA

Model No. NM-EJM5D-A

LNB conveyor + 3 production modulars in-line setup

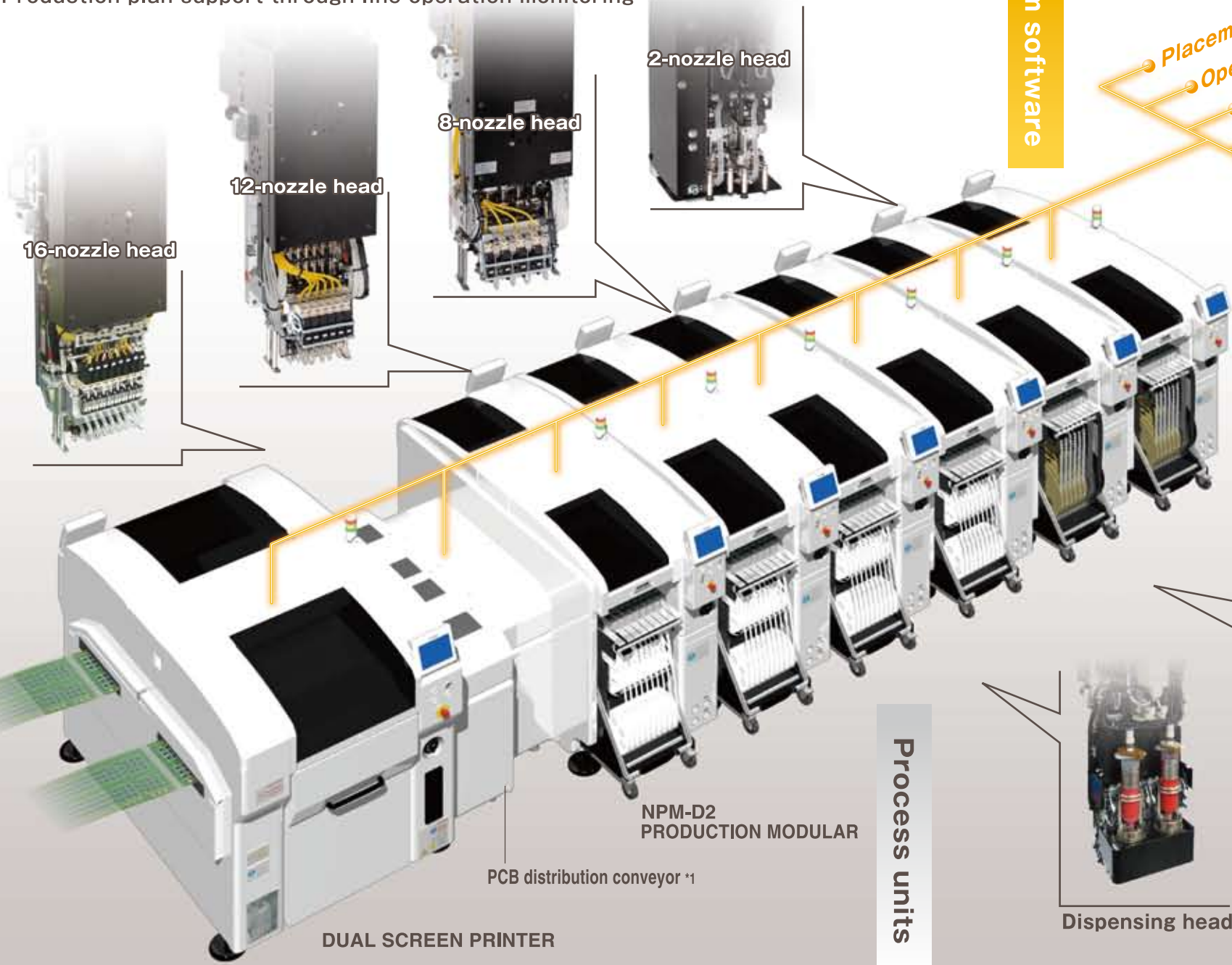


*It may not conform to Machinery Directive and EMC Directive in case of optional configuration and custom-made specification.

- 1 High area productivity with total mounting lines**
Higher productivity and quality with printing, placement and inspection process integration
- 2 Configurable modules allow flexible line setup**
Head location flexibility with plug-and-play functions
- 3 Comprehensive control of lines, floor and factory with system software**
Production plan support through line operation monitoring

Placement heads

Dual printer



System software

- Placement height control system
- Operation navigation system
- APC system
- Component Verification option
- Automatic changeover option
- Host communication option

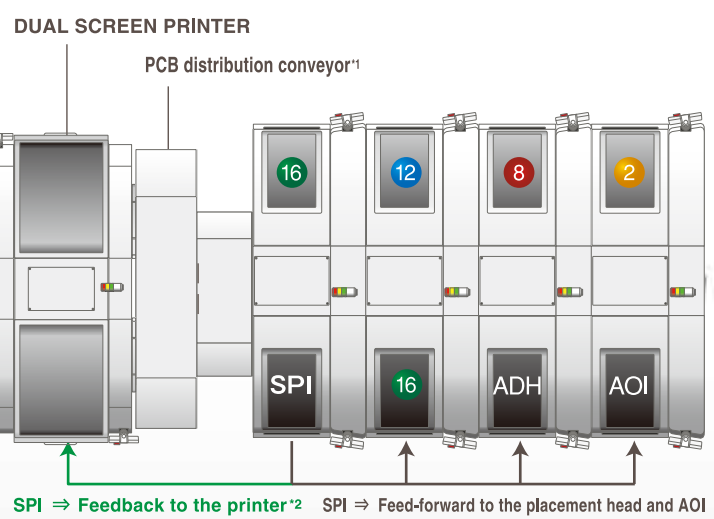


NPM-DGS Data Creation System

Total line solution

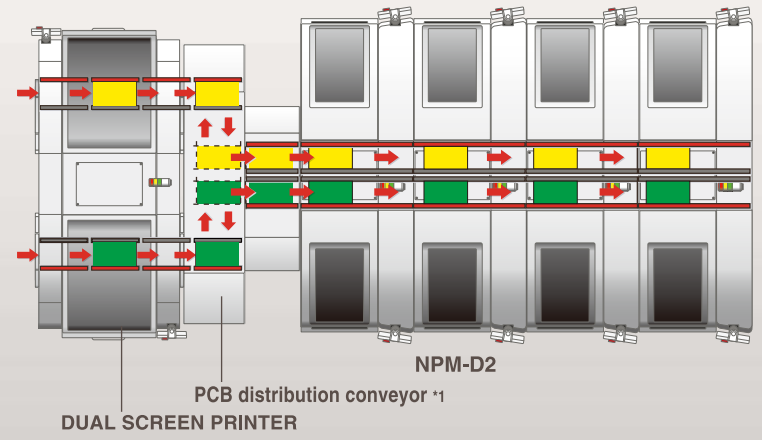
Smaller-footprint modular lines by installing inspection heads

- Provides high-quality manufacturing with in-line inspection
- 16 ... 16-nozzle head ADH ... Adhesive dispensing head
 - 12 ... 12-nozzle head SPI ... Solder Inspection
 - 8 ... 8-nozzle head AOI ... Component Inspection
 - 2 ... 2-nozzle head



Multi-Production Line

Mixed production with different type substrates on the same line is also provided with the dual conveyor.



Supply units

*1: Please prepare the PCB distribution conveyor from other companies
*2: SPD, SP70 can be connected to APC system

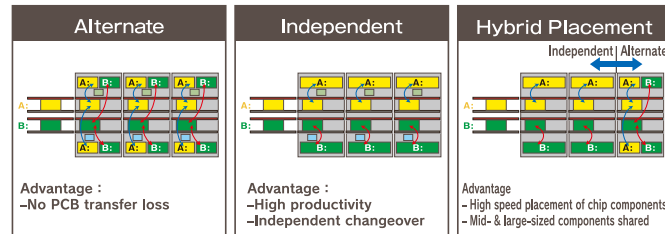
High productivity

Employs dual mounting method

Alternate, Independent & Hybrid Placement

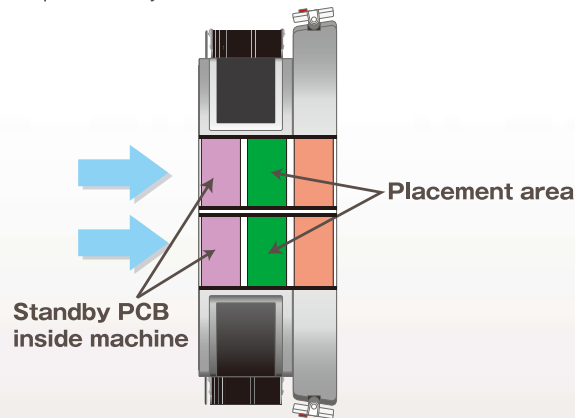
Selectable "Alternate" and "Independent" dual placement method allows you to make good use of each advantage.

- **Alternate:** Front and rear heads execute placement on PCBs in front and rear lanes alternately.
- **Independent:** Front head executes placement on PCB in front lane and rear head execute placement on rear lane.



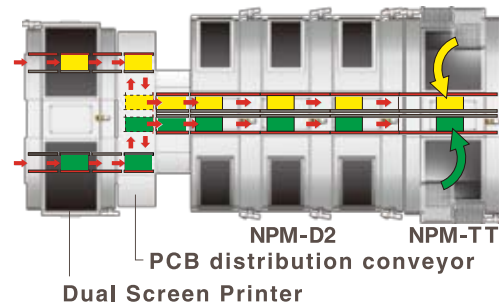
PCB exchange time reduction

Allow standby PCB with less than L=250mm at upstream conveyor inside machine to reduce PCB exchange time and improve productivity.



High productivity through fully independent placement

Achieved independent placement of tray components by directly linking with NPM-TT. Capable of fully independent placement of tray components improving cycle time of mid-, large-size component placement with 3-nozzle head. Output of entire line is enhanced.



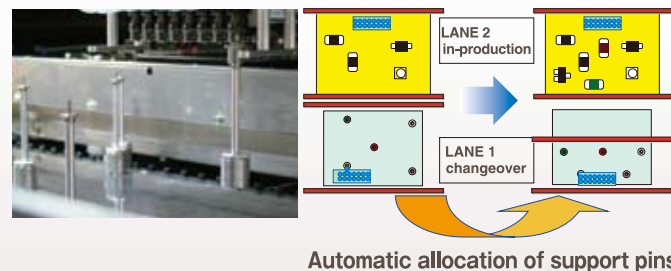
01005" (0402) chip placement with higher speed (option)

Shorter recognition time for 01005" (0402) chips can reduce placement time by 3% than conventional.

*IPC9850 compliant, 16-and 12-nozzle head

Automatic replacement of support pins (option)

Automate position change of support pins to enable non-stop changeover and help save man-power and operation errors.



Quality improvement

Placement height control function

Based on PCB warpage condition data and thickness data of each of the components to be placed, the control of placement height is optimized to improve mounting quality.



*Vertical line camera features
(1) Detecting component thickness per pick-up
(2) Detecting tombstone and skew defects
(3) Detecting nozzle height
For further information, see the specification.

Operating rate improvement

Feeder location free



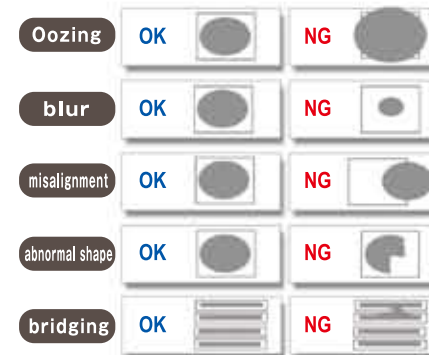
Within same table, feeders can be set anywhere. Alternate allocation as well as setting of new feeders for next production can be done while the machine is in operation.

Feeders will require off-line data input by support station (option).

Solder Inspection (SPI) · Component Inspection (AOI) Inspection head

Solder Inspection

- Solder appearance inspection



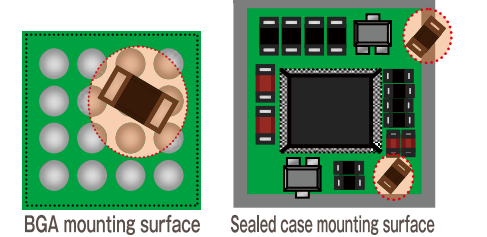
Mounted component Inspection

- Appearance inspection of mounted components



Pre-mounting foreign object*1 inspection

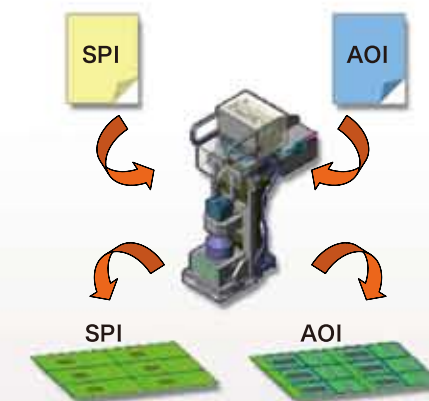
- Pre-mounting foreign object inspection of BGAs
- Foreign object inspection right before sealed case placement



*1: Foreign object is available to chip components.

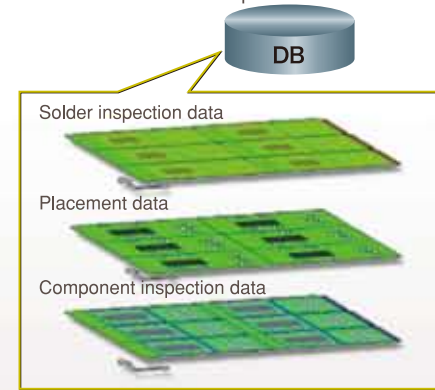
SPI and AOI automatic switching

- Solder and component inspection is switched automatically according to production data.



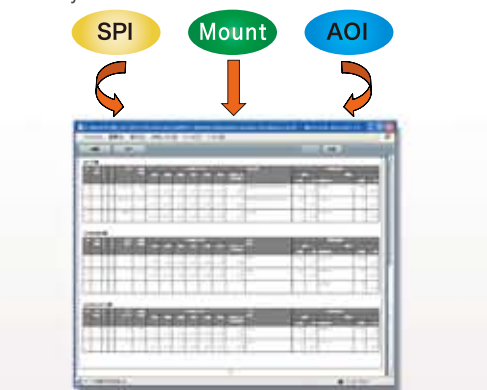
Unification of inspection and placement data

- Centrally managed component library or coordinate data does not require two data maintenance of each process.



Automatic link to quality information

- Automatically linked quality information of each process assists your defect cause analysis.



Adhesive Dispensing

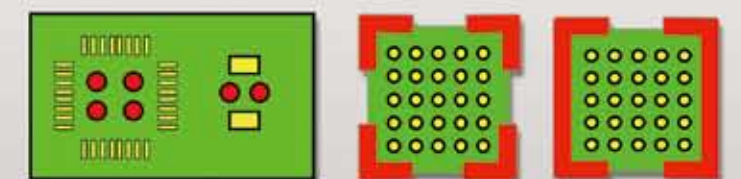
Dispensing head

Screw-type discharge mechanism

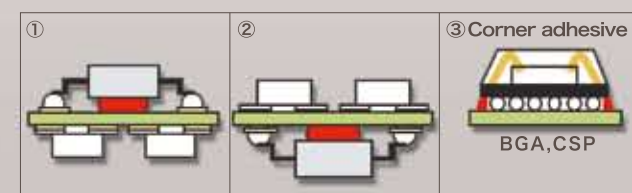
- Panasonic's NPM has the conventional HDF discharge mechanism, which ensures the high-quality dispensing.



Supports various dot/drawing dispensing patterns



- High accuracy sensor (option) measures local PCB height to calibrate dispensing height, which allows for non-contact dispensing on PCB.



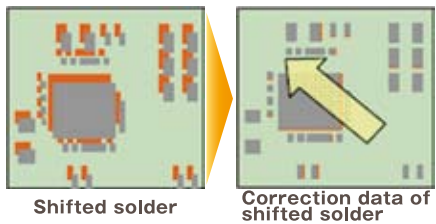
* Pre-demonstration is required.

High-quality mounting

APC system*

Feedback to the printing machine

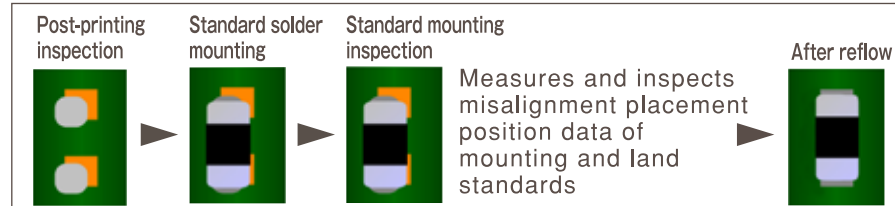
- Based on the analyzed measurement data from solder inspections, it corrects printing positions. (X, Y, θ)



*3D inspection equipment of another company can be also connected. Please inquire with your sales representative for more details.

Feedforward to mounting heads

- Solder position measurement and feedforward
- Chip components (0402C/R ~)
- Package component (QFP, BGA, CSP)

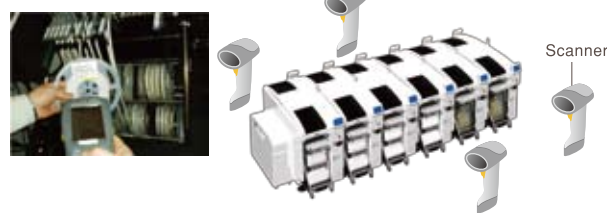


Feedforward to AOI

- Position inspection on APC offset position

Component Verification option

Prevents setup errors during changeover Provides an increase of production efficiency through easy operation

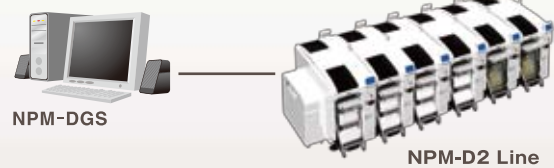


- Component setup error prevention
Prevents setup errors through verifying the NPM-D2 downloaded production data and component barcode data
- Array data activesync function
There's no need to select array data; data is verified with the NPM-D2
- Interlock function
Equipment stops when it has an incorrect and/or incomplete verification
- Navigation function
Clearly provide a verification task with data display and Intelligent feeder performance in sync
- Scanner selection
Users can choose either a wired or wireless scanner (PDA)

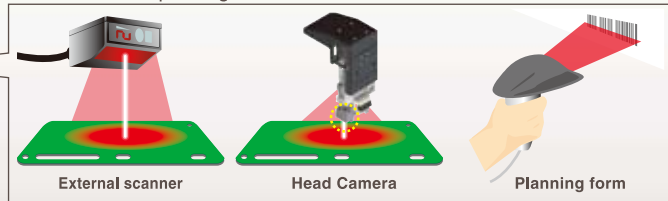
High productivity

Automatic changeover option

Supporting changeover (production data and rail width adjustment) can minimize time loss



- PCB ID read-in type
PCB ID read-in function is selectable from among 3 types of external scanner, head camera or planning form



Off-line setup support station

With the support stations, offline feeder cart setup is possible anywhere even outside of the manufacturing floor.

- Two types of Support Stations are available.

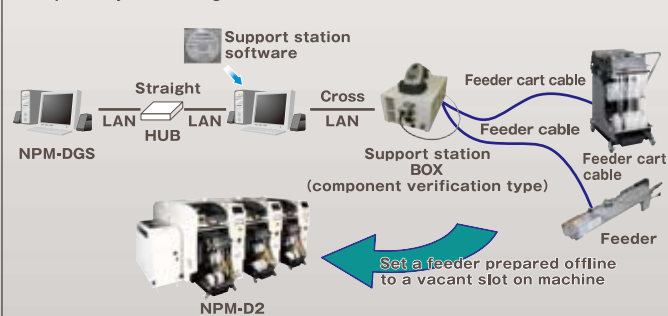
① Power Supply Station:
Batch Exchange Cart Setup – Provides power to all feeders in cart. Feeder Setup – provides power to individual feeders.



② Component Verification Station:
Additional to the power supply station, Component Verification feature is added to this model. The station will navigate you to the location where feeders need exchange.



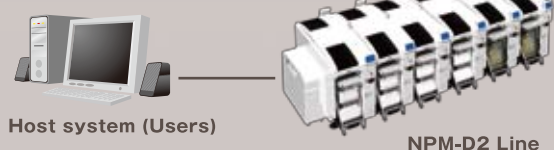
Example of system configuration)



Open interface

Host communication option

Able to standardize the interfacing with your systems currently used. Provides data communication with our standard interfaces.



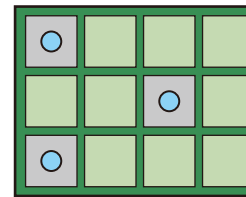
- Events
Outputs a real-time event of equipment
 - Other company's component verification
Communicates with your component verification systems
 - Component management data
 - Component remaining quantity data: Outputs component remaining quantity data
 - Trace data: Outputs data linked with component information (*1) and PCB information (*2)
- (*1) Requires input of component information with a component verification option or an other company's component verification system I/F
(*2) Requires input of PCB information with automatic changeover option

PCB information communication function

Information of mark recognitions done on first NPM machine in line is passed on to downstream NPM machines. Which can reduce cycle time utilizing the transferred information.

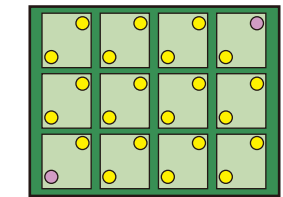
[Subject for communication]

Bad mark recognition

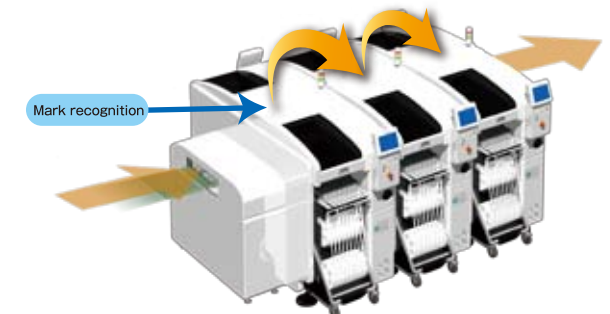


Legend: Good (Green square), Bad (Blue square)

Pattern mark recognition



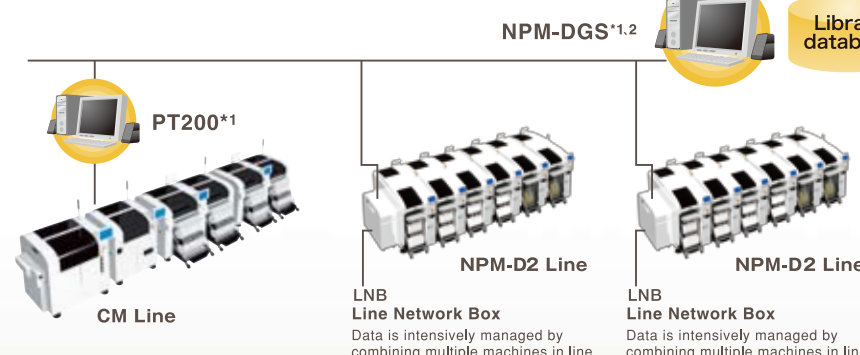
Legend: Master mark (Purple circle)



Data Creation System

NPM-DGS (Model No. NM-EJS9A)

The software package helps to achieve high productivity through integral management of creation, editing and simulation of production data and library.

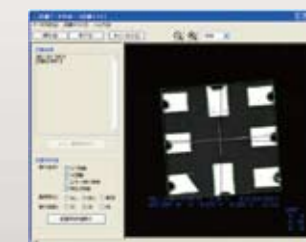


*1: A computer must be purchased separately.
*2: NPM-DGS has two management functions of floor and line level.

Offline Camera Unit (option)

Minimizes time on machine for parts library programming and assists equipment availability and quality. Parts library data is generated using the line camera for NPM-D2.

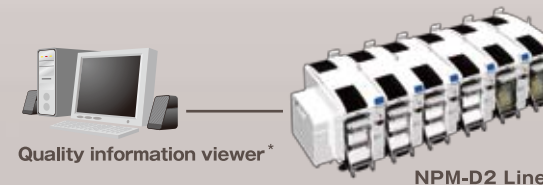
Conditions not possible on a scanner such as Illumination conditions, and recognition speeds, can be checked offline assuring quality enhancements and equipment availability.



Quality improvement

Quality information viewer

This is software designed to support a grasp of changing points and analysis of defect factors through the display of quality-related information (e.g., feeder positions used, recognition offset values and parts data) per PCB or placement point. In case of our inspection head introduced, the defect locations can be displayed in association with quality-related information



*PC is required for every line.



Example of use of quality information viewer

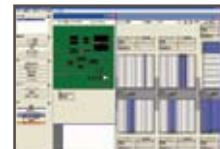
Identifies a feeder used for mounting of defect circuit boards. And if, for example, you have many misalignments after splicing, the defect factors can be assumed to be due to:
1) splicing errors (pitch deviation is revealed by recognition offset values)
2) changes in component shape (wrong reel lots or vendors)
So you can take quick action to the misalignment correction.

Multi-CAD import



Almost all CAD data can be retrieved by macro definition registration. Properties, such as polarity, also can be confirmed on screen in advance.

Simulation



Tact simulation can be confirmed on screen in advance so that line total operation ratio can increase.

PPD/LWS Editor



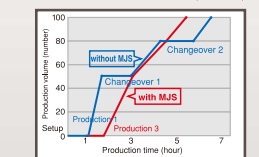
With quickly and easily compiling placement and inspection head data on the PC display during operation, time loss can be minimized

Component library



A component library of all placement machines including the CM series on floor can be registered to unify data management.

Mix Job Setter (MJS)



Off-line component data creation option



With creating off-line component data using a store-bought scanner, productivity and quality can be improved.